					Docket Number	<u> </u>	Application N	lumber			
INFORMATION DISCLOSURE CITATION IN AN APPLICATION						<u> </u>					
					M4065.0127/P127-A Not Yet Assigned						
					Applicant(s)						
					Kie Y. Ahn et al.						
					Filing Date Group Art Unit						
					September 12, 2000		2815				
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*EXAMINER INITIAL	REF	DOCUMENT NO.	DATE		NAME	CLASS	SUBCLASS	FILING II APPROI	P		
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767	В	5,530,288	6/25/96	Stone		257	700	10/12/94			
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EXAMINER: Initial if citation considered, whether	or not citation is in conformance with MPEP Section 609; Draw line thro	g
	Include copy of this form with next communication to Applicant.	
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DATE CONSIDERED